CW CBLPM1.E1

CERAMOS® Gen 4.H

Highly efficient lightsource, slim package design





Applications

- Flash & Autofocus

Features:

- Package: SMD ceramic package with silicone resin
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: Cx = 0.36, Cy = 0.37 acc. to CIE 1931 (• white)
- Corrosion Robustness Class: 3B
- CRI: 80 (min.), 82 (typ.)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2); 8 kV acc. to IEC 61000-4-2, level 4 (contact discharge)



CW CBLPM1.E1-MXMZ-R

Ordering Information Luminous Flux 1) Type $I_F = 1000 \text{ mA}$ Φ_V Φ_V



Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T _{op}	min.	-40 °C
	- 1-	max.	85 °C
Storage Temperature	T _{stg}	min.	-40 °C
	otg	max.	85 °C
Junction Temperature ²⁾	T _j	max.	150 °C
Junction Temperature Pulse ³⁾	T	max.	175 °C
Forward Current ²⁾	I _F	min.	30 mA
T _s = 25 °C		max.	500 mA
Forward Current pulsed ³⁾	I F pulse	max.	2000 mA
D = 0.016 ; T _s = 25 °C	. puloe		
Reverse current 4)	I _R	max.	200 mA



Characteristics

 $I_{_{
m F}}$ = 1000 mA; $T_{_{
m S}}$ = 25 °C

Parameter	Symbol		Values
Chromaticity Coordinate 5)	Cx Cy	typ. typ.	0.36 0.37
Viewing angle at 50% ${\rm I_v}$	2φ	typ.	120 °
Forward Voltage ⁶⁾ I _F = 1000 mA	V _F	min. typ. max.	2.70 V 3.05 V 3.70 V
Reverse voltage (ESD device)	V _{r esd}	min.	5 V
Reverse voltage ⁴⁾ I _R = 20 mA	V _R	max.	1.2 V
Color Rendering Index 7)	R _a	min. typ.	80 82
Electrical thermal resistance junction/solderpoint with efficiency $\eta_{\rm e}$ = 27 %	$R_{thJS elec.}$	typ.	8.0 K / W

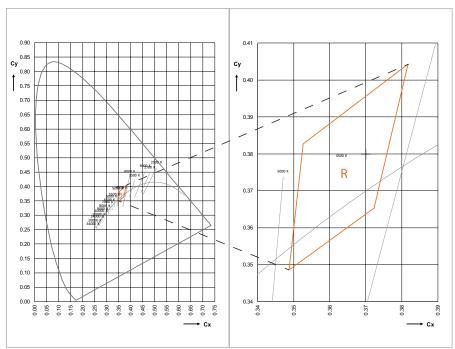


Brightness Groups

Group	Luminous Flux ¹⁾ I _F = 1000 mA min. Φ _v	Luminous Flux ¹⁾ I _F = 1000 mA max. Φ _V	
MX	180 lm	210 lm	
MY	210 lm	240 lm	
MZ	240 lm	280 lm	



Chromaticity Coordinate Groups



Chromaticity Coordinate Groups ⁵⁾

Group	Сх	Су
R	0.3526	0.3827
	0.3817	0.4043
	0.3723	0.3653
	0.3487	0.3486

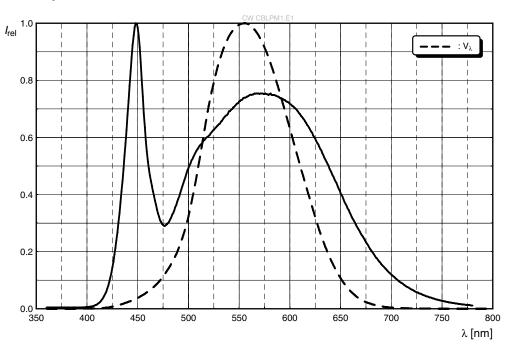
Group Name on Label

Example: MX-R	
Brightness	Color Chromaticity
MX	R



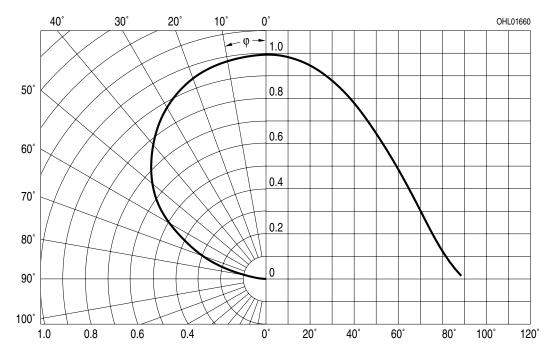
Relative Spectral Emission⁸⁾

 $I_{rel} = f(\lambda); I_{F} = 1000 \text{ mA}; T_{J} = 25 \text{ }^{\circ}\text{C}$



Radiation Characteristics⁸⁾

I_{rel} = f (φ); T_J = 25 °C

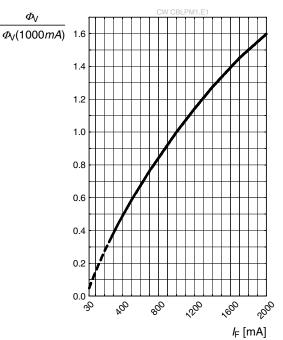




Forward current ^{8), 9)}

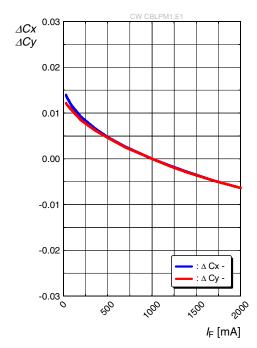
Relative Luminous Flux^{8), 9)}

 $\Phi_{v}/\Phi_{v}(1000 \text{ mA}) = f(I_{F}); T_{J} = 25 \text{ °C}$



Chromaticity Coordinate Shift⁸⁾

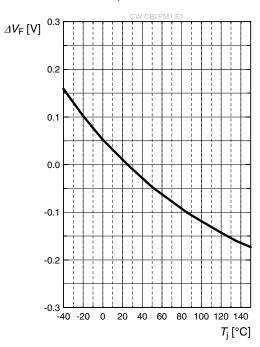
 ΔCx , $\Delta Cy = f(I_F)$; $T_J = 25 \ ^{\circ}C$





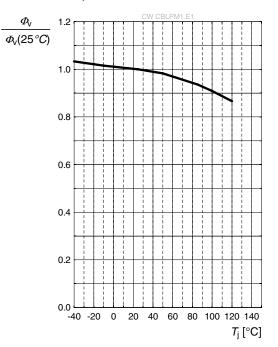
Forward Voltage⁸⁾

 $\Delta V_{_{\rm F}} = V_{_{\rm F}} - V_{_{\rm F}}(25 \ ^{\circ}{\rm C}) = f(T_{_{\rm J}}); I_{_{\rm F}} = 1000 \ {\rm mA}$



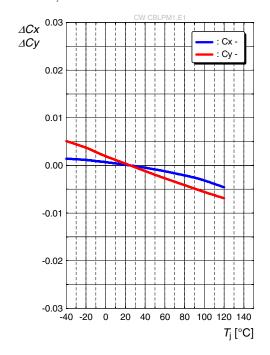
Relative Luminous Flux⁸⁾

 $\Phi_v/\Phi_v(25 \text{ °C}) = f(T_i); I_F = 1000 \text{ mA}$



Chromaticity Coordinate Shift⁸⁾

 ΔCx , $\Delta Cy = f(T_j)$; $I_F = 1000 \text{ mA}$





$I_{F} = f(T)$ *I*_F [mA] ⁵⁵⁰ 500 450 400 350 160 K/W 300 : 110 K/W : 60 K/W 250 18 K/W 200 150 100 50 Do not use below 30 mA 0 0 20 40 60 80 *T* [°C]

Max. Permissible Forward Current

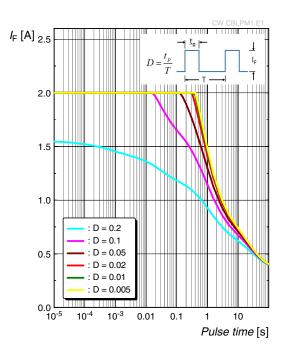
Note:

Deratings strongly relate on the boundary conditions of each individual device:

- The DC-derating on the left represents several thermal resistance values Rth JA (Junction/Ambient) as examples.
- The shown pulse-deratings represent just one of alterative options for use. For further information please refer to application note "Thermal Management of Flash LEDs".

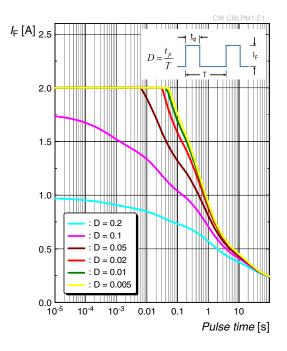
Permissible Pulse Handling Capability

 $R_{th JA el} = 160 \text{ K/W}; T_A = 25 \text{ °C}; \text{ still air; FR4}$



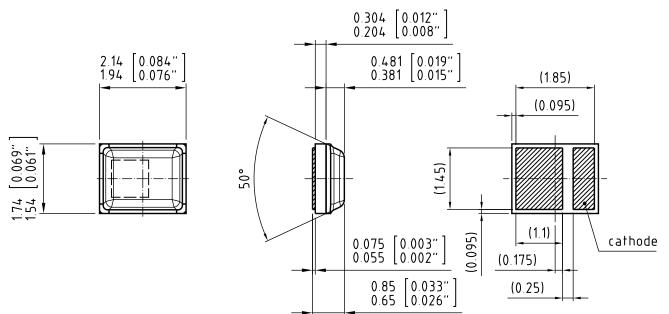
Permissible Pulse Handling Capability

 $R_{th JA el}$ = 160 K/W; T_A = 85 °C; still air; FR4





Dimensional Drawing ¹⁰⁾



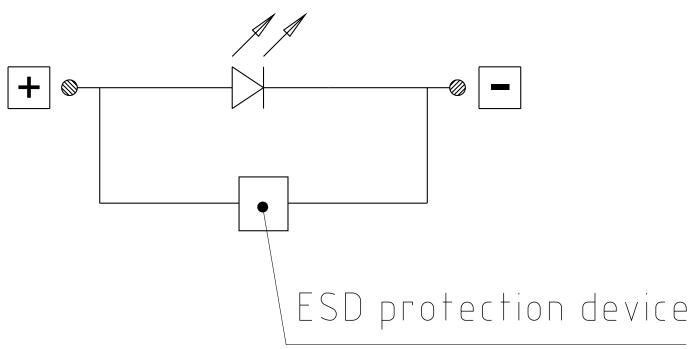
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Further Information:

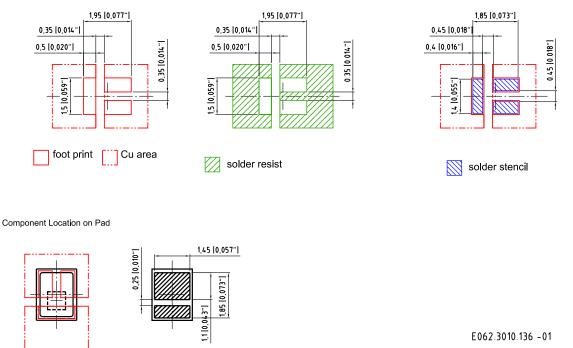
Approximate Weight:	8.2 mg
Corrosion test:	Class: 3B Test condition: 40°C / 90 % RH / 15 ppm H ₂ S / 14 days (stricter than IEC 60068-2-43)
ESD advice:	The device is protected by ESD device which is connected in parallel to the Chip.



Electrical Internal Circuit



Recommended Solder Pad¹⁰⁾

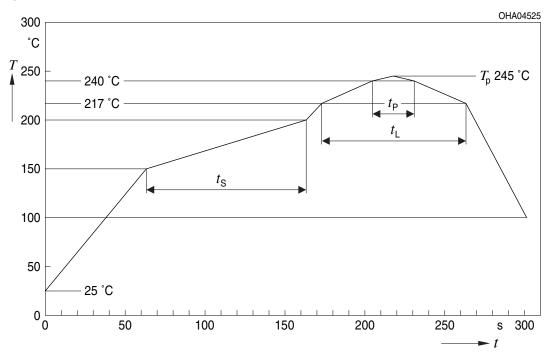


For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



Profile Feature	file Feature Symbol Pb-Free (SnAgCu) Assembly			embly	Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t _s T _{smin} to T _{Smax}	t _s	60	100	120	S
Ramp-up rate to peak ^{*)} T_{smax} to T_{p}			2	3	K/s
Liquidus temperature	TL		217		°C
Time above liquidus temperature	t		80	100	S
Peak temperature	Τ _Ρ		245	260	°C
Time within 5 °C of the specified peak temperature T_p - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

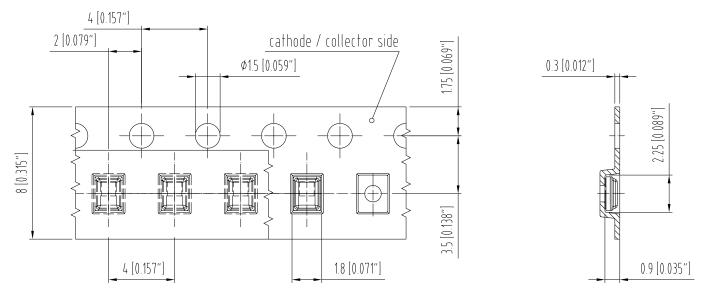
All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Opto Semiconductors

CW CBLPM1.E1

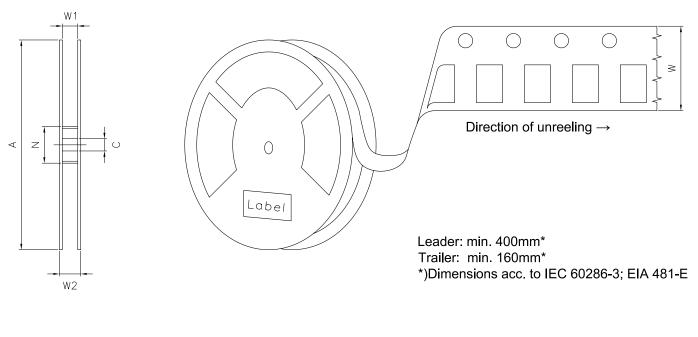
Taping ¹⁰⁾



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Tape and Reel ¹¹⁾

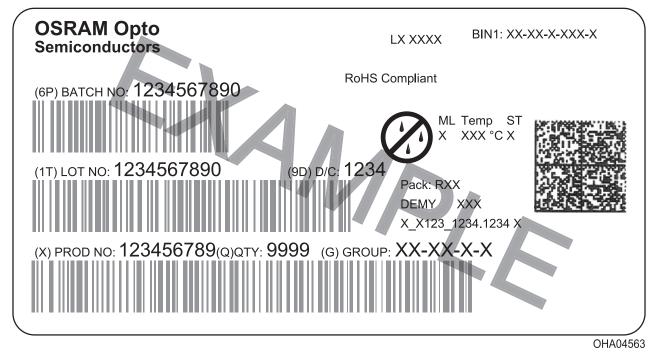


Reel Dimensions

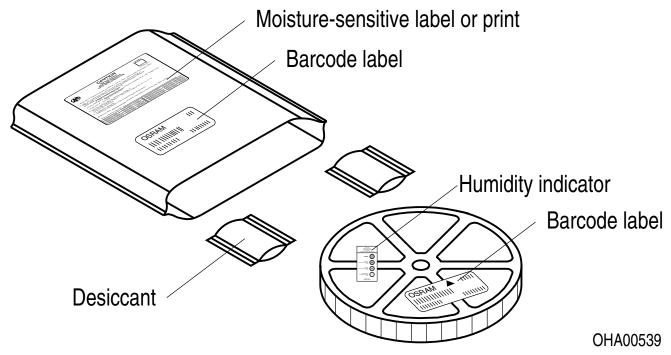
А	W	N _{min}	W ₁	$W_{2 \max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	4000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials ¹⁰⁾





Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



Glossary

- ¹⁾ **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 8 % and an expanded uncertainty of ± 11 % (acc. to GUM with a coverage factor of k = 3).
- ²⁾ **Operating Conditions:** Operating conditions according DC-derating (Max. Permissible Forward Current)
- ³⁾ **Operating Conditions:** Operating conditions according Pulse-derating (Permissible Pulse Handling Capability)
- ⁴⁾ **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- ⁵⁾ **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 0.005 and an expanded uncertainty of ± 0.01 (acc. to GUM with a coverage factor of k = 3).
- ⁶⁾ **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of k = 3).
- ⁷⁾ **Color reproduction index:** Color reproduction index values (CRI-RA) are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 2 and an expanded uncertainty of ± 3 (acc. to GUM with a coverage factor of k = 3).
- ⁸⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁹⁾ **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- ¹⁰⁾ **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ¹¹⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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